

## AMENDMENTS TO THE CLAIMS

Claims 1-16 (Cancel)

Claim 17 (New) An apparatus for polishing a substrate on which a circuit wiring pattern is formed, comprising:

    a polishing table having a polishing surface,

    a substrate carrier having a lower surface for holding a substrate and bringing the substrate into contact with said polishing surface,

    an attitude control mechanism for keeping the lower surface of the substrate carrier parallel with the polishing surface, and

    an image processing apparatus for recognizing a circuit wiring pattern formed on the substrate,

    wherein said substrate carrier is positionable over the polishing table and the image processing apparatus.

Claim 18 (New) An apparatus claimed in claim 17, further comprising:

    a slurry supply nozzle for supplying slurry between the substrate and the polishing surface of the polishing table, and

    a water nozzle for removing the slurry from the surface of the substrate.

Claim 19 (New) An apparatus claimed in claim 18, wherein the image processing apparatus is positioned at an outer peripheral portion of the polishing table.

Claim 20 (New) An apparatus claimed in claim 18, wherein the slurry supply nozzle supplies a first slurry and a second slurry.

Claim 21 (New) An apparatus claimed in claim 20, further comprising a water jet nozzle for removing the first slurry from the polishing surface before the slurry supply nozzle supplies the second slurry.

Claim 22 (New) An apparatus claimed in claim 21, wherein the substrate carrier is set to extend outwardly of the outer peripheral portion of the polishing table during polishing operation.

Claim 23 (New) An apparatus claimed in claim 22, wherein the attitude control mechanism comprises at least an electromagnetic coil and a drive circuit for energizing the electromagnetic coil.

Claim 24 (New) An apparatus for polishing a substrate on which a circuit wiring pattern is formed, comprising:

    a polishing table having a polishing surface,

    a substrate carrier having a lower surface for holding a substrate and bringing the substrate into contact with said polishing surface,

    an attitude control mechanism for keeping the lower surface of the substrate carrier parallel with the polishing surface, and

    an image processing apparatus for recognizing a circuit wiring pattern formed on the substrate positioned at an outer peripheral portion of the polishing table,

    wherein the substrate carrier is set to extend outwardly of the outer peripheral portion of the polishing table during polishing operation.

Claim 25 (New) An apparatus claimed in claim 24, further comprising:

    a slurry supply nozzle for supplying slurry between the substrate and the polishing surface of the polishing table, and

    a water nozzle for removing the slurry from the surface of the substrate.

Claim 26 (New) An apparatus claimed in claim 25, wherein the slurry supply nozzle supplies a first slurry and a second slurry.

Claim 27 (New) An apparatus claimed in claim 26, further comprising a water jet nozzle for removing the first slurry from the polishing surface before the slurry supply nozzle supplies the second slurry.

Claim 28 (New) An apparatus claimed in claim 27, wherein the attitude control mechanism comprises at least an electromagnetic coil and a drive circuit for energizing the electromagnetic coil.

Claim 29 (New) An apparatus for polishing a substrate on which a circuit wiring pattern is formed, comprising:

    a polishing table having a polishing surface,

    a substrate carrier for holding a substrate and bringing the substrate into contact with said polishing surface,

    an attitude control mechanism for preventing the substrate carrier from being inclined, and

    an image processing apparatus for recognizing a circuit wiring pattern formed on the substrate,

    wherein said substrate carrier is positionable over the polishing table and the image processing apparatus.

Claim 30 (New) An apparatus claimed in claim 29, further comprising:

    a slurry supply nozzle for supplying slurry between the substrate and the polishing surface of the polishing table, and

    a water nozzle for removing the slurry from the surface of the substrate.

Claim 31 (New) An apparatus claimed in claim 30, wherein the attitude control mechanism comprises at least an electromagnetic coil and a drive circuit for energizing the electromagnetic coil.

Claim 32 (New) An apparatus for polishing a substrate on which a circuit wiring pattern is formed, comprising:

- a polishing table having a polishing surface,
- a substrate carrier for holding a substrate and bringing the substrate into contact with said polishing surface,
- an attitude control mechanism for preventing the substrate carrier from being inclined, and
- an image processing apparatus for recognizing a circuit wiring pattern formed on the substrate positioned at an outer peripheral portion of the polishing table.

Claim 33 (New) An apparatus claimed in claim 32, wherein the substrate carrier is positionable over the polishing table and the image processing apparatus.

Claim 34 (New) An apparatus claimed in claim 33, further comprising:

- a slurry supply nozzle for supplying slurry between the substrate and the polishing surface of the polishing table, and
- a water nozzle for removing the slurry from the surface of the substrate.

Claim 35 (New) An apparatus claimed in claim 34, wherein the attitude control mechanism comprises at least an electromagnetic coil and a drive circuit for energizing the electromagnetic coil.